We claim:

1. An integrated circuit package comprising:

(a) an integrated circuit die having at least one circuit etched thereon; and

(b) a housing containing said integrated circuit die,

wherein said integrated circuit die is electrically coupled to said housing using at least one wire bond; and wherein said wire bond(s) has (have) an inductance associated therewith; and wherein said wire bond inductance is used to facilitate operation of said at least one circuit.

2. A method of providing inductance to facilitate operation of a circuit contained in an integrated circuit package comprising making available wire bond inductance to said circuit.

3. The use of wire bond inductance in an integrated circuit package to facilitate operation of a circuit contained in an integrated circuit package.

4. The method of claims 2 wherein said circuit is contained in an integrated circuit die housed in said integrated circuit package.

5. A use as claimed in claim 3 wherein said circuit is contained in an integrated circuit die housed in said integrated circuit package.

6. The integrated circuit package of claim 1 wherein said at least one of circuit is an impedance inverter.

7. The method of claim 2 wherein said circuit is an impedance inverter.

8. The use of claim 3 wherein said circuit is an impedance inverter.

9. The integrated circuit package of claim 1 wherein said at least one of circuit is a discrete filter.

10. The method of claim 2 wherein said circuit is a discrete filter.

11. The use of claim 3 wherein said circuit is a discrete filter.

12. The integrated circuit package of claim 1 wherein said at least one circuit comprises on-die and off-die components.

13. The method of claim 2 said circuit comprises on-die and off die components.